P E FORM PTO-1449

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U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE

ATTY. DOCKET NO. MICRON.084C1C1

APPLICATION NO. 10/634,134

MATION DISCLOSURE STATEMENT
BY APPLICANT

USE SEVERAL SHEETS IF NECESSARY)

APPLICANT Jiang et al.

FILING DATE August 4, 2003

GROUP Unknown

2823

				U.S. PATENT DOCUMENTS	······································		
EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE (IF APPROPRIATE)
sae	1.	781,230	01/31/05	Rodman	_		
SAG	2.	2,935,420	05/03/60	Linden			
IH	3.	3,339,526	9/05/67	Bradley et al.			
PAG	4.	3,839,037	10/1/74	Fromson			
JAG	5.	3,923,541	12/2/75	Healy			
JAG	6.	3,930,465	01/06/76	Schuierer			
DAG	7.	3,990,926	11/9/76	Konicek			
DAG	8.	4,113,899	9/12/78	Henry et al.	_		
SAC	9.	4,282,271	8/4/81	Feldstein			
SAG	10.	4,364,975	12/82	Cork et al.			
249	11.	4,474,311	10/02/84	Petrecca	_		
DAT.	12.	4,603,656	08/05/86	Jaye, Jr.			
AG	13.	4,762,601	9/9/88	Krulik et al.			
JAC	14.	4,772,496	9/20/88	Maeda et al.			
SAG	15.	4,913,082	4/3/90	Silbermann et al.	_		
SH	16.	4,938,850	7/3/90	Rothschild et al.			
JAC	17.	5,028,454	7/2/91	Lytle et al.			
AG	18.	5,118,362	7/2/92	St. Angelo et al.			
JAC	19.	5,194,313	3/16/93	Hupe et al.	_		
J/K	20.	5,206,052	4/27/93	Nakaso et al.			
SH	21.	5,262,041	11/16/93	Gulla			
JAG	22.	5,342,501	08/94	Okabayashi			
SAE	23.	5,441,629	08/95	Kosaki			
JAC	24.	5,458,819	10/10/95	Lashmore et al.			
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TAL	26.	5,500,108	3/19/96	Goldberg			
SAG	27.	5,512,131	04/98	Kumar et al.			

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DATE CONSIDERED

July 29 2004

*EXAMINER: INITIAL IF CITATION CONSIDERED, WHETHER OR NOT CITATION IS IN CONFORMANCE WITH MPEP 609; DRAW LINE THROUGH CITATION IF NOT IN CONFORMANCE AND NOT CONSIDERED, INCLUDE COPY OF THIS FORM WITH NEXT COMMUNICATION TO APPLICANT.

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APPLICATION NO. 10/634,134 # PTO-1449 U.S. DEPARTMENT OF COMMERCE ATTY. DOCKET NO. PATENT AND TRADEMARK OFFICE MICRON.084C1C1 INF BY APPLICANT **APPLICANT** Jiang et al. USE SEVERAL SHEETS IF NECESSARY) FILING DATE GROUP 2823 August 4, 2003 **Unknown**

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EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE (IF APPROPRIATE)
JAG	28.	5,583,073	12/10/96	Lin et al.	_		
JAG	29.	5,603,849	2/18/97	Li			
JAG	30.	5,618,634	4/8/97	Hosoda et al.			
JAG	31.	5,725,807	03/98	Thorn et al.			
JAG	32.	5,810,940	9/22/98	Fukazawa et al.	_		
SAG	33.	5,897,368	04/99	Cole, Jr. et al.	-		
DAT	34.	5,911,865	6/15/99	Yih			
SAS	35.	5,925,931	7/20/99	Yamamoto			

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SAG	36.	K. Baudrand, J. Bengston, "Electroless Plating Processes - Developing Technologies for Electroless Nickel, Palladium, and Gold," Metal Finishing, Sept. 1995, pp.55-57.
JAG	37.	W.J. Hawk, "Electroless Palladium for Electronics," Metal Finishing, March 1986, pp.11-12.
SAG	38.	J.K. Lim, J.S. Russo, E. Antonier, "Electroplated Palladium Coating As a Nickel Migration (Thermal) Barrier," Plating and Surface Finishing, March 1996, pp.64-67.
SAG	39.	H. Nawafune, S. Mizumoto, M. Haga, E. Uchida, "Electroless Palladium Plating from an Ethylenediamine Complex Bath using Phosphite as a Reducing Agent," Transactions of the Institute of Metal Finishing, Vol. 74, #1, pp.21-24.
JAG	40.	Rao, "Multilevel Interconnect Technology," Chapter: Manufacturing, p.141. (Jake Unknown)
JAG	41.	P. Steinmetz, S. Alperine, A. Friant-Costantini, P. Josso, "Electroless Deposition of Pure Nickel, Palladium and Platinum," Surface and Coatings Technology, 43/44 (1990), pp. 500-510.

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